

CALL FOR ABSTRACTS



SEPTEMBER
16-19, 2019
CONFERENCE CENTRE
PISA
ITALY

22nd EUROPEAN MICROELECTRONICS AND PACKAGING CONFERENCE & EXHIBITION

www.empc2019.org

The Structures of Microelectronics

Pisa, the charming city in the famous Tuscany region, is a visitors' paradise. The International Airport "Galileo Galilei" is only 2.7 km away from the Conference Centre and it has become one of the main Italian airports with flights to over 74 destinations all around Europe and globally. It is also a hub for low-cost airlines (www.pisa-airport.com). The venue is easy to access also via public transportation, railway and car.

EMPC-2019 in Pisa offers the best of microelectronics packaging and interconnection technologies, providing top quality coverage of technological innovation in this field. The four days will comprise Tutorials/Short Courses and the Conference and Exhibition during 16th to 19th September at the Palazzo Dei Congressi, an ideal venue which includes excellent lecture auditoria, exhibition space and a great social venue. The event will be complemented by social events for which IMAPS has a great tradition. Pisa, where tradition, art, culture and business meet harmoniously, is ideal also to extend your visit.

Researchers and innovators in industry and academia are cordially invited to submit papers on the range of Microelectronics Technologies and Photonics Technologies, for oral or poster presentation at the Conference. All oral and poster presentations will be assessed to the same standard and accorded the same value. The full papers presented as oral or posters will be eligible for inclusion in IEEE Xplore and IMAPS Source.

Please visit <https://www.conftool.org/empc2019> to set up an account and upload your Abstract

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TOPICS

ADVANCED PACKAGING: Single Chip and Multi Chip Packaging, Wafer Level Packaging, 3D-WLP, 3D-IC, CoB, SiP, SoC, Systems-Integration Technologies, Embedded Passives on Wafers and Substrates, High Frequency and High Power Packaging, LTCC Technologies, Micro-Vias and Build-Up Technologies, Lab-on-Chip, Lab-on-Substrate, Molecular Electronics.

SUBSTRATE TECHNOLOGIES: Inorganics, Organics, Co-fired, Flexibles, HD PCBs, Laminates, Printed, Microfluidics, Substrates Design and Technologies.

INTERCONNECTION TECHNOLOGIES: Thick and Thin Film Technologies, Wire Bonding, Bumping, Flip Chip Bonding, Cu/Low-k Wafers, Through Silicon Vias, Advances in Soldering, Adhesive Joining, Connectors.

MORE THAN MOORE: The future of IC shrinkage, the future options for IC packaging.

MEMS: MEMS Based Sensors and Actuators Packaging, RF-MEMS, Optical MEMS, Bio-MEMS, WiFi modules

OPTOELECTRONICS: Silicon Photonics, Power LED Assembly, Packaging and Light Guiding, Packaging of Optoelectronic Modules suitable for Gb/s Fibre Optic Communication, LiFi modules.

SOLAR ENERGY & PHOTOVOLTAICS: Packaging Design to improve Efficiency of Photovoltaic modules, Reliability and Qualification Approaches.

NANO TECHNOLOGIES: Smart Materials, Interconnections, Nano-Scale Packaging: Applications and Reliability.

GREEN ELECTRONICS: Recovery and Recycling, Base material technologies.

MEDICAL ELECTRONICS: Applications, Design, Development, Manufacturing that comply with complex and demanding regulations and market requirements.

POWER ELECTRONICS: Application in Consumer, Telecom, Automotive, Wearable, Space and Defence, Fuel Cells, Battery Technologies.

SMART TEXTILES: Wearables, Materials, Technologies, Applications, Markets, Reliability.

MANUFACTURING TECHNOLOGIES AND MATERIALS: Process Development, New Equipment, Clean Room Technologies, Yield Improvement, Cost and Cycle Time Reduction, Green Manufacturing, Micromachining, Dispensing, Printing, Deposition, Adhesives, Encapsulants, Underfills, Moulding Compounds, Advanced Solder Alloys, Halogen Free Materials, Dielectrics, Ceramics.

MODELLING: Electrical Modelling and Signal Integrity: Time and Frequency Domain Analysis of Interconnection and Packaging Technologies, Thermal Characterisation and Cooling Solutions, Modelling and Simulation Methodology for Characterisation of Advanced Packaging, Modules and Systems, Novel Cooling Techniques, Mechanical Modelling and Structural Integrity, Thermo-Mechanical Stress Analysis, Vibration and Shock Tests.

THERMAL MANAGEMENT: Techniques, Heatsinks, Heat pumping.

RELIABILITY and QUALITY: Specialised topics, Components, Counterfeits, Board and System Level Reliability Assessment, Failure Analysis, Interfacial Adhesion, Accelerated Testing, Reliability Engineering, Inspection and Test, Obsolescence Engineering, Prognostics.

COMPUTING: Ambient Intelligence methods and products, Circuits and Systems, Touch Screen technologies.

APPLICATIONS: Medical, Bio-Tec, Telecoms, Mobile, Smart Phones, RFID, Automotive, Aerospace, Robotics, Consumer, Structural.

BUSINESS ASPECTS: Electronics and Photonics, In-house or Outsource?, Markets, Supply Chain, Distribution, Microelectronics packaging and assembly industry.

EMPC 2019 Committee

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Venue: Conference and Exhibition will be held at Palazzo dei Congressi, Pisa - Italy - www.palazzodeicongressi.pisa.it

Abstract submission opening: June 2018

Deadline for abstract submission: January 15th 2019

Deadline for paper submission: June 30th 2019

A copy of the full paper must be submitted to be included in the event Proceedings and databases.